

JAN20

NanoXplore

FACTS SHEET



1 avenue de la Cristallerie
92310 SEVRES
France

Tel: +33 (0)1 7787 0048
info@nanoxplore.com
www.nanoxplore.com



STATUS

NG medium

NG large

NG ultra

Ultra-150

STATUS



DOCUMENTATION



SUCCESS STORIES

ROOM FOR USERS

- **Current version** : v2.9.6 issued 05/12/2019
- **V2.9.6 new features** : On top of bugs fixed,
 - Bitstream NG-Large,
 - NX_R5_L component provided in NX library,
 - NX_HSSL_L component provided in NX library,
 - DFI DDR2 IP available (provided example),
 - FIFO IP available (in Nxcore),
 - Support for preplace Fes in specific tiles with PrePlaceFile option.
- **V2.9.6 tweaks**:
 - Updated encryption mechanism,
 - IP licensing mechanism,
 - Remote obsolete threshold options,
 - Add check of NX_WFG connections in first step of Synthesis.
- **Next release** : v2.9.6 expected CW1951



DOCUMENTATION

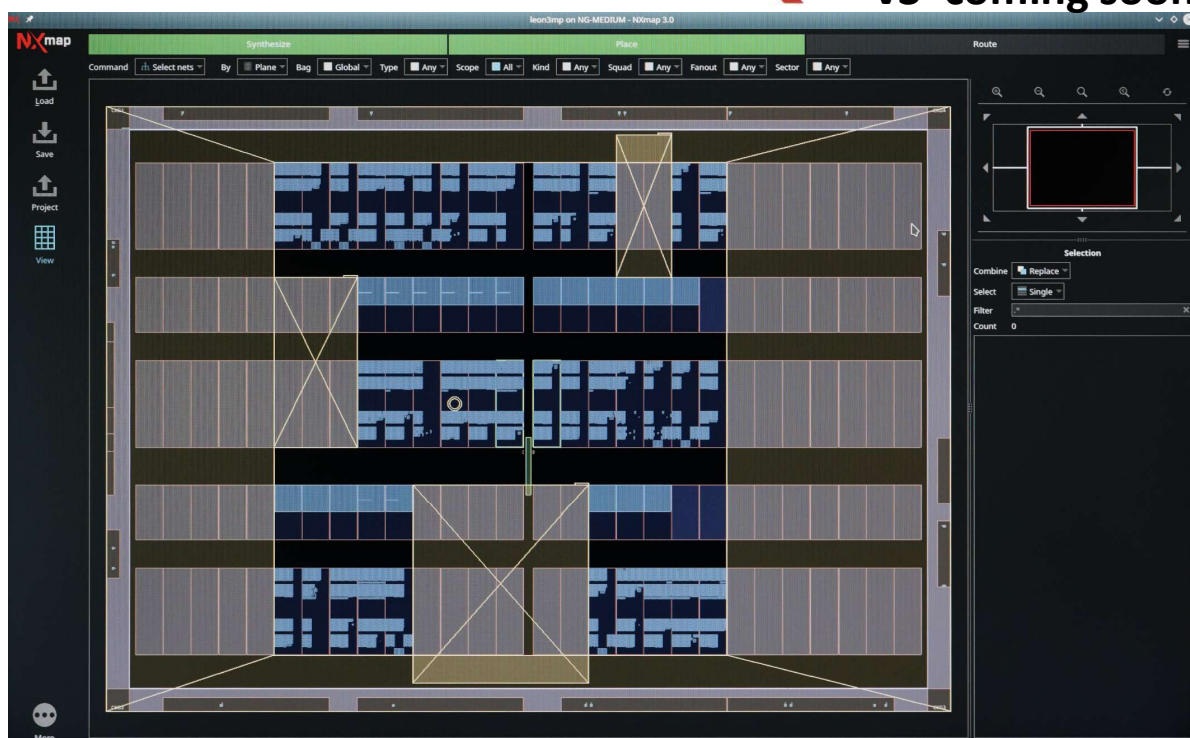
<http://download.nanoxplore.com>

✓ NXmap Reference Guide:	v2.0 (22oct18)
✓ NXmap User Manual	v2.9.4 (18jun19)
✓ NXmap using Python IDE	v1.1 (17jun19)
✓ NX Library Guide	v1.5 (17jun19)
✓ NXBase2 User Manual:	v2.2.2 (18jun19)
✓ Cookbook:	v1.4 (5sep19)
✓ Nxscope User Manual & startup	v1.1 (21oct19)
✓ NX SpW Bank IP	v1.0 (28nov18)
✓ NX SERDES IP	v1.0 (21oct19)
✓ NX DFI DDR2 IP	v1.0 (5dec19)
✓ NG-Medium datasheet:	v1.9 (18oct19)
✓ NG-Medium Cfg Guide:	v1.1 (21oct19)
✓ NG-Medium NXPE	v1b (17jan19)
✓ NG-Medium IBIS models	v1 (14nov18)
✓ NG-Medium Devkit-v3 UG:	v1.04 (18feb19)
✓ NG-Medium Radiation report:	v3.3 (23oct19)
✓ NG-Large datasheet	v1.0 (3dec18)
✓ NG-Large Pkg & pinout	v1.0 (21oct19)
✓ NG-Large NXPE	v1.a (17jan19)
✓ NG-Large Devkit-v1 UG	v1.0 (23oct19)

See you at
SEFUW#05 – 17-19mar20
 @ Noordwijk (NL)



v3 coming soon ...



NG medium

Technology: 65nm CMos

Organic Package: FG625

Ceramic Packages: CQ352, LG625, CG625

Industrial status:

Proposed QA level: PR, M, MP, B and E grades

Proposed QA flows: PR, M, Q and V grades

NXmap v2/v3	Proto	EK v4	M/S parts Organic	Mil Parts Ceramic	Spa parts Ceramic	SMD Or ESCC
NOW/Apr20	NOW	NOW	SEP20	NOW	NOW	SEP20

News: NXmap training course done successfully in Dec19.

Qualification: NX1H35AS (= NG-Medium Metal-fix) qualification running, acc. DLA instructions.
NG-Medium/FG625 selected for the 1st ESCC9000P (Plastic) qualification.

Flight Heritage: Floriposat-1 launch with Amazonia-1 scheduled JUN20.

NG large

Technology: 65nm CMos

Organic Package: FF1752

Ceramic Packages: LF1752, CF1752

Industrial status:

Proposed QA level: PR, M, MP grades

Proposed QA flows: PR, M, Q and V grades

NXmap v2/v3	Proto PR	EK v1	Mil parts Organic	Mil parts Ceramic	Spa parts Ceramic	SMD Or ESCC
NOW/Apr20	NOW	NOW	SEP20	Q1CY21	Q2CY21	TBD

News: Design validated. 1st NG-Large Evaluation Kits delivered end-19.

Qualification: Started.

Flight Heritage: Several projects identified. 1st Flight heritage expected H1CY21.

NG ultra

Technology: 28nm FDSOI

Organic Package: FF1752

Ceramic Packages: LF1752, CF1752

Industrial status:

Proposed QA level: PR, M, MP, B and E grades

Proposed QA flows: PR, M, Q and V grades

NXmap v3	1st-run Proto	EK v1	M/S Parts Organic	Mil Parts Ceramic	Spa Parts Ceramic	SMD Or ESCC
Q4CY20	Q4CY20	Q1CY21	Q3CY21	Q4CY21	Q2CY22	TBD

News: Design completed. 1st-run samples expected within coming months.

Qualification: Too early.

Flight Heritage: N/A.

Next device will be the

Ultra-150

Definitions

- NXmap, Prototype(s), Product Evaluation Kit (EK): Availability dates.
- Military & Space parts Organic: Organic product industrialized & ORDER entry OPEN.
- Military parts Ceramic: Ceramic product, M/MP flow(s) industrialized & ORDER entry OPEN.
- Space parts Ceramic: Ceramic product, Q/V flows industrialized & ORDER entry OPEN.
- SMD or ESCC: Expected date when either the SMD or ESCC specification number will become valid & active.

NX RHBD FPGA Products

NG medium			NG large			NG ultra			
Device		Details	NX1H35AS		Details	NX1H140TSP		Details	NX2H540TSC
Capacity	FPGA		C65Space	FPGA		C65Space	FPGA		C28FD Space
ASIC Gates			550 000			1 900 000			8 000 000
Logic Modules		3x Tiles + 2CGBs			7x Tiles + 4CGBs			15x Tiles + 9CGBs	
Register		384DFF*28*3rows	32 256		384DFF*48*7rows	129 024		384DFF on 15rows	505 344
LUT-4		408LUT*28*3rows	34 272		408LUT*48*7rows	137 088		408LUT on 15rows	536 928
Carry		96CY*28*3rows	8 064		96CY*48*7rows	32 256		96CY on 15rows	126 336
Embedded RAM	SOC		2,9Mb	SOC		9,9Mb	SOC		33Mb
DPRAM		28RAM*2* 48Kb	2.688K		48RAM*4* 48Kb	9.216K		672RAM * 48Kb	32.256K
Core Register File		28RF*2*3rows	168		48RF*2*7rows	672		672RF *2*2	2 688
Core Register File Bits		168*64*(16+6)bits	168K with ECC		672*64*(16+6)bits	672K with ECC		2688*32*18	1 512K hardened
Clocks / PLL		4 CLK / 4 PLL	4		4 CLK / 4 PLL	4		7 CLK / 7 PLL	7
Additional Features	SOC			SOC			SOC		
SpaceWire PHY (8 IOBs)		2x/Complex IOBank	16		2x/Complex IOBank	20		2x/Complex IOBank	20
DDR3/4 PHY (11IOBs)		2x/Complex IOBank	16		2x/Complex IOBank	20		2x/Complex IOBank	20
DSP Blocks		From 2 CGBs	112		From 4 CGBs	384		From 9 rows	1344
SpaceWire link I/F 430Mbps		CODEC	1		CODEC	1		CODEC	1
SERDES Tx/Rx		-	-		4 Hex x 6 SERDES	24x @ 6,25Gbps		8 Quad x 4 SERDES	32x @ 12,5Gbps
Hard IP Processor core		-	-		ARM Cortex-R5	1		ARM Cortex-R52	4
SoC Peripherals	NXcore	TBD	NXcore	TBD	DALHIA	YES			
Design Security			NO			NO			YES
Inputs / Outputs	I/O		-	I/O		-	I/O		-
I/O banks		8 Complex + 5 Simple	13		10 Complex + 14 Simple	24		10 Complex + 4 Simple	14
Packages - User I/Os	PKG			PKG			PKG		
CQ352		48*48mm / 0,5mm	192		-	-		-	-
LG/CG625		29*29mm / 1mm	374		-	-		-	-
FG625		27*27mm / 1mm	374		-	-		-	-
LF1752 & CF1752					45*45mm / 1mm	684		45*45mm / 1mm	436 + SoC 308
FF1752					42,5*42,5mm / 1mm	684		42,5*42,5mm / 1mm	436 + SoC 308

Ceramic

NG-Medium

- ◆ CQ352
 - CQFP technology
 - 352pins
 - 0,5mm pitch
- ◆ LG625
 - Fine pitch 1mm
 - 29*29mm body
- ◆ CG625
 - CLASP
 - Or Copper Ribbon

NG-Large

- ◆ LF1752
 - Fine pitch 1mm
 - 45*45mm body
- ◆ CF1752
 - CLASP
 - Or Copper Ribbon

NG-Medium

- ◆ FG625
 - Fine pitch 1mm
 - 27*27mm body
 - Wire-bonded
 - Lead-free

NG-Ultra

Same as NG-Large

- ◆ LF1752
- ◆ CF1752

NG-Large

- ◆ FF1752
 - Fine pitch 1mm
 - 42,5*42,5mm body
 - Flip-chip
 - Lead-free

Ultra-150

- ◆ LF484 & CF484

- Fine pitch 1mm
- CQ256 (TBC)
- 0,5mm pitch

Ultra-150

- ◆ FF484
 - Fine pitch 1mm
 - 23*23mm body
 - Flip-Chip
 - Lead-free

Organic

CERAMIC & ORGANIC packages ballprint & pinout compatible
 NG-Medium: FG625 with LG625,
 NG-Large: FF1752 with LF1752,
 NG-Ultra: FF1752 with LF1752 (TBC),
 Ultra-150: LF484 with FF484 (TBC).

© 2020 Nanoxplore SAS Company Confidential
 Copy not authorized without written approval



NX Packages

Ceramic	M	Q	V	Organic	M	MP	B	E
WLAT	✗	✓	✓	WLAT	✗	✗	✓	✓
TID / Report	✗	✓	✓	TID / Report	✗	✗	✓	✓
SLDC	✗	✓	✓	SLDC	✗	✗	✓	✓
T/C	✗	10cy	10cy	T/C	✗	10cy	10cy	10cy
IVI	2010B SPL	2010B 100%	2010A 100%	IVI	2010B SPL	2010B SPL	2010B 100%	2010A 100%
Pind-Test	✗	On Request	✓	CSAM	✗	✗	✓	✓
Serialization	✗	✗	✓	Serialization	✗	✗	✗	✓
Burn-In	✗	160h	240h	Burn-In	✗	48h	160h	240h
PDA	✗	5%	5%	PDA	✗	✗	1%	1%
Electrical Test	-55°C & +125°C	25°C then -55°C & +125°C	25°C then -55°C & +125°C R&R	Electrical Test	-55°C & +125°C	+25°C then -55°C & +125°C	+25°C then -55°C & +125°C	25°C then -55°C & +125°C R&R
QCI	✗	✓	✓	LAT 1/2/3	✗	✗	✓	✓
EVI	SPL	✓ 100%	✓ 100%	EVI	SPL	SPL	100%	100%
CoC	✗	✓	✓	CoC	✗	✗	✓	✓

NX QA Flows

Feel free to contact support@nanoxplore for any questions about NanoXplore HW or SW issues



NXmap Training course

Please note, next NanoXplore NXmap training course which will hold at NX headquarters in Sèvres (F-92310) will be scheduled 28/30apr20. Cost is 300€/person.

The following one will happen Q4CY20.

Please contact sales@nanoxplore.com for additional details and to register.

NX web site

Please visit our brand new web site

<https://www.nanoxplore.fr>

<https://www.nanoxplore.com>

A screenshot of the NanoXplore website. The header features a navigation menu with links: COMPANY, PRODUCTS, SUPPORT, SALES, CAREERS, NEWS, and CONTACT. The NanoXplore logo is centered in the header. The main content area has a blue background with a circuit board pattern. It features the text 'SoCs, FPGA, eFPGA' in large white letters, followed by a paragraph describing the company as a privately owned fabless company based in France, offering a comprehensive portfolio of SoCs and FPGA devices for aerospace, defense, and industrial markets. A red 'LEARN MORE' button is positioned below the text. The footer section is white and contains the heading 'Corporate profile', a paragraph of text, and another red 'LEARN MORE' button.

COMPANY PRODUCTS SUPPORT SALES **NX** NanoXplore CAREERS NEWS CONTACT

SoCs, FPGA, eFPGA

NanoXplore is a privately owned fabless company based in France. The company offers a comprehensive portfolio of SoCs and FPGA devices for aerospace, defense and industrial markets. Products include a leading radiation hardened FPGA portfolio.

LEARN MORE

Corporate profile

NanoXplore is a privately owned fabless company based in France. The company offers a comprehensive portfolio of SoCs and FPGA devices for aerospace, defense and industrial markets. Products include a leading radiation hardened FPGA portfolio.

LEARN MORE

Feel free to contact support@nanoxplore for any questions about NanoXplore HW or SW issues